

IN THE CLAIMS:

Applicants present the following amendments in accordance with the revision to 37 C.F.R. § 1.121 (Manner of Making Amendments) outlined in the Revised Notice dated February 13, 2003.

Kindly amend the claims as follows:

AI 1. (Amended) A light emitting diode comprising:

a surface mount package;

a metal lead frame having mass sufficient to provide low thermal resistance and wherein the metal lead frame comprises three anode contact pads and one cathode contact pad ~~including at least one anode contact pad and at least one cathode contact pad;~~

a reflector positioned within the package; and,

a semiconductor die comprising a transparent substrate and a light emitting component, the semiconductor die positioned within the package between an anode contact and a cathode contact over the reflector.

2. (Original) The light emitting diode of claim 1 further comprising a focusing dome operative to refract light emitted from the semiconductor die and light reflected from the reflector to create a predetermined radiation pattern.

3. (Original) The light emitting diode of claim 2 wherein the radiation pattern comprises a 120 degree illumination pattern.

4. (Original) The light emitting diode of claim 1 wherein the reflector comprises a truncated cone shape.

5. (Canceled)

6. (Original) The light emitting diode of claim 1 wherein the lead frame comprises a lead frame having a thermal resistance less than 300 K°/W.
7. (Original) The light emitting diode of claim 1 wherein the lead frame comprises copper.
8. (Original) The light emitting diode of claim 1 wherein the lead frame comprises silver-plated copper.
9. (Original) The light emitting diode of claim 1 wherein the light emitting component comprises a GaN-based compound semiconductor and the substrate comprises sapphire.
10. (Original) The light emitting diode of claim 1 wherein the light emitting component comprises an AlInGaP compound semiconductor and the substrate comprises GaP.
11. (Original) The light emitting diode of claim 1 wherein the light emitting component and the substrate are arranged side-by-side over the reflector.
12. (Original) The light emitting diode of claim 1 wherein the substrate is positioned on top of the light emitting component over the reflector.
-